ASSOCIATION CONNE	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mf	g Inforr	mation		
upplier Info	rmation															
Company name* Com				Company unique ID			Unique ID Authority					Response Date*				
nsemi												2024-05-11				
Contact Name			Title - Contact			F	Phone - Contact*					Email - Contact*				
Product-Env-Sto	ewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com					
Authorized Representative* Title -				Fitle - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Sto	ewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com						
Requ	uester Item Number Mfr Item		em Number Mfr Item Name					ate Version Ma		Manufacturing Site		V	eight* UOM		M	Unit Type
		NCP103BMX330TCG 150 mA CMOS			LDO, HZ option, V	option, Vout=3.3V 2024-05-11			N	MY1		1.	1.74			Each
Ianufacturi	ng Proccess Informati	on														
Termi	nal Plating / Grid Array Mat	Plating / Grid Array Material Te		Terminal Base Alloy J		J-STD-020 MSL Rating		Peak Process Body Temperature		e Max Time	Max Time at Peak Temper		ture Number of Reflow Cycles		S	
Precio Sn)			CU Alloy 1		1		260		С		30 seco		s 3			
Comments							_		<u> </u>		_				<u> </u>	<u> </u>
vel 1 - maximu	m time at peak temperatur	e during so	ldering is 10-30	0 seconds												
or more inform	ation regarding material c	omposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the complance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg
Die Attach Epoxy	0.02	mg		Epoxy resin	proprietary data		0.002	mg
			Supplier	Cumene hydroperoxide	80-15-9		0.0001	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0009	mg
			Supplier	Silver (Ag)	7440-22-4		0.017	mg
Lead Frame	0.76	mg	Supplier	Tin (Sn)	7440-31-5		0.0019	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0017	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0019	mg
			Supplier	Copper (Cu)	7440-50-8		0.7545	mg
Mold Compound-Black	0.87			Epoxy resin	proprietary data		0.0409	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.087	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0009	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.7003	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0409	mg
Plating	0.01	_	Supplier	Silver (Ag)	7440-22-4		0	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			В	Nickel (Ni)	7440-02-0		0.0099	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg